

# PERFREZ® Series



**PERFREZ® XL15**

## Purity Solution for Both Static and Dynamic Applications

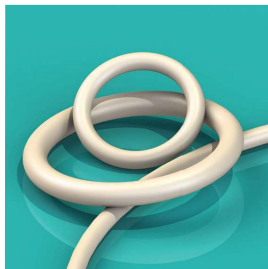
**PERFREZ® XL15** is a translucent compound made of a semicrystalline nano-filler. This compound is developed to handle the most demanding fluorine, chlorine and oxygen plasmas as well as the most aggressive acids and solvents used in semiconductor processing. It is also recommended for extreme applications in the bio-analytical industry.

## Purity Solution for Both Static and Dynamic Applications

**PERFREZ® XL12** features superior physical properties with exceptionally low particle generation. XL12 offers a low Coefficient of Thermal Expansion (CTE) that mitigates risk of extrusion, while offering outstanding plasma resistance and erosion, especially with aggressive fluorine based process.



**PERFREZ® XL12**



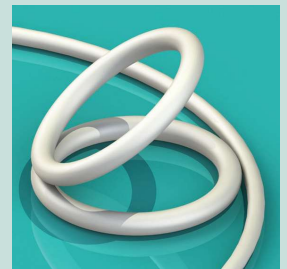
**PERFREZ® XL11**

## Enhanced Plasma Resistance and Physical Strength

**PERFREZ® XL11** offers superior plasma resistance especially aggressive fluorine based process. It also features the excellent physical properties with low CTE that mitigate any risk of extrusion due to thermal expansion.

## High Temperature Perfluoroelastomer That Combines The Benefits of Chemical Compatibility with Thermal Stability for Sub-Fab Applications

**PERFREZ® 6022** is specially developed to handle aggressive oxygen and fluorine based exhaust gases while providing excellent thermal properties.



**PERFREZ® 6022**



**PERFREZ® 5033**

## Specialty Hybrid - Ideal and Economic Solution for Better Performance

**PERFREZ® 5033** solves the problem where an FKM (known as Viton® in all their many mixes and grades) cannot handle the process chemistries but a FFKM (perfluoroelastomer) is an 'overkill' solution.

# PERFREZ® Series

## High Temp. Perfluoroelastomer for Plasma Applications

High  
Temp.

**PERFREZ® MX7** is the newest line of product portfolio products specially developed to handle extreme high temperature combined with aggressive oxygen and fluorine based plasma, while generating minimum particles.



**PERFREZ® MX7**



**PERFREZ® PXC-Ultra**

## Ultra Pure FFKM for Harsh Semiconductor Applications

**PERFREZ® PXC-Ultra** a high purity upgrade of PXC which is also specialized for semiconductor equipment with harsh conditions, especially with stringent requirement on contamination. As effective as the original version, it also offers excellent resistance to a wide variety of chemistries including acids/bases which makes it a great alternative for wet applications, while keeping the same temperature endurance.

## High Performance Seal Solution for Harsh Semiconductor Applications

**PERFREZ® PXC** is a specialized line of Perfluoroelastomers for semiconductor equipment wet manufacturing processes. PXC offers excellent resistance to a wide variety of chemistries including acids/bases. PXC has a maximum service temperature of 260°C.



**PERFREZ® PXC**



**PERFREZ® XT**

## Chemical Resilient Perfluoroelastomer for the Most Harsh Plasma Applications

**PERFREZ® XT** is specially designed for abatement, SubFab and Fab applications which require a broad range of chemical compatibility and excellent mechanical properties.

**Note:**

*Slight color variations may be observed in actual ASNA products (seals / bonded gates). Variations are considered to be normal phenomena in seal manufacturing.*

*Due to the curing process, small marks or dark spots may be observed in actual ASNA products. It is not indicative of foreign matter and will not impact on product performance.*

*Please contact ASNA engineers if there are any questions or concerns.*